506788015 07/28/2021

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
OSAMU MUNEKATA	07/16/2021
MASATO SHIRATORI	07/16/2021

RECEIVING PARTY DATA

Name:	SENJU METAL INDUSTRY CO., LTD.	
Street Address:	23, SENJU-HASHIDO-CHO	
City:	ADACHI-KU, TOKYO	
State/Country:	JAPAN	
Postal Code:	120-8555	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17426137

CORRESPONDENCE DATA

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using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Email: nppatent@nixonpeabody.com, dsias@nixonpeabody.com

Correspondent Name: NIXON PEABODY, LLP Address Line 1: 799 NINTH STREET, NW

Address Line 2: SUITE 500

Address Line 4: WASHINGTON, D.C. 20001

ATTORNEY DOCKET NUMBER:	434620-000283
NAME OF SUBMITTER:	JEFFREY L. COSTELLIA
SIGNATURE:	/Jeffrey L. Costellia, Reg. No. 35,483/
DATE SIGNED:	07/28/2021

Total Attachments: 3

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PATENT 506788015 REEL: 056999 FRAME: 0537

Docket	No.	

ASSIGNMENT

	WHEREAS, (I/we), (1) Hiroyos	<u>hi KAWASAKI,</u> (2) <u>Osa</u> ı	mu MUNEKATA, and (3)
Masai	to SHIRATORI a citizen of Japan,	residing at (1)Tokyo	, Japan
(2)	Tokyo, Japan (3)	Tokyo, Japan	, have invented a
	SOLDER ALLOY, SOLDER PO	WDER, AND SOLDER	JOINT
for wl	hich (I/we) have executed applicat	ion papers for U.S. paten	t application filed herewith; and

WHEREAS, <u>SENJU METAL INDUSTRY CO.</u>, <u>LTD.</u> having a place of business located at <u>23</u>, <u>Senju-Hashido-cho</u>, <u>Adachi-ku</u>, <u>Tokyo 120-8555 Japan</u>, is desirous of acquiring the exclusive right, title and interest in and to said invention and in and to the Letters Patent to be granted and issued therefor in the United States of America and its territories and possessions, and all countries foreign thereto;

NOW, THEREFORE, for a valuable consideration, the receipt of which is hereby acknowledged, (I/we), (1) Hiroyoshi KAWASAKI, (2) Osamu MUNEKATA, and (3) Masato SHIRATORI, do sell, assign, transfer and set over unto the said SENJU METAL INDUSTRY CO., LTD., its successors and assigns, the full and exclusive right, title and interest in and to said invention, and in and to any and all Letters Patent to be granted and issued therefor, not only for, to and in the United States of America, its territories and possessions, but also for, to and in all other countries including all priority rights under the International Convention; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said SENJU METAL INDUSTRY CO., LTD., its successors and assigns, in accordance with this Assignment.

#325303

P3 38 WOUS 050 1320 A 2/3

Docket	No
[ASSIGNMENT CONTINUATION]	
Re: U.S. Patent Application entitled:	
Inventor: Hiroyoshi KAWASAKI	
WITNESS MY HAND at(city, state, country)	, this
day of,	
Name: Hiroyoshi KA WASAKI	
Re: U.S. Patent Application entitled: SOLDER ALLOY, SOLDER POWE	DER, AND SOLDER JOINT
Inventor: Osamu MUNEKATA	
WITNESS MY HAND at Tokyo, Japan (city, state, country)	, this

#325303

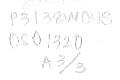
(month)

16th

(date)

2021

(year)



		Docket No.	***************************************
Ocamu Munekala			
Name: Osamu MUNEKATA			
Re: U.S. Patent Application entitled:	SOLDER ALLOY JOINT	7, SOLDER POWDEF	R, AND SOLDER
Inventor: <u>Masato SHIRATORI</u>			
WITNESS MY HAND atTokyo	o, Japan (city, state, co	untry)	_, this
16thday of	July		
(datc)	(month)	(year)	
Masato Shiratori			
Name: Masato SHIRATORI			

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